



*Application Note*

**MC92600 WarpLink Quad**

**Configuring Unused Channels to Minimize Power**

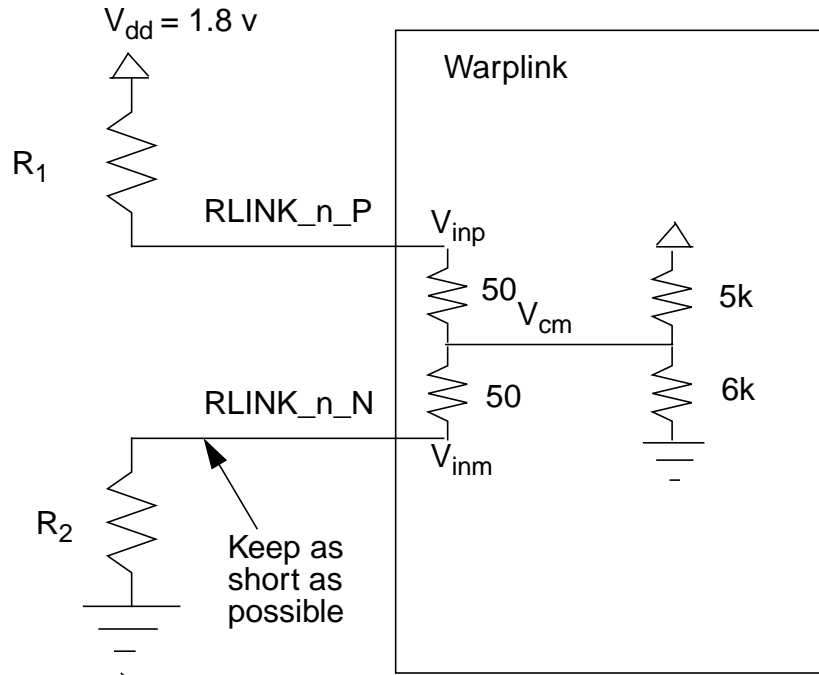
This application note details how to configure an unused Warlink Channel to minimize power consumption of this device.

## 1.1 Configuration Requirements

Warning: Warplink is designed to allow word alignment (32 bit alignment) for all 4 channels. If a channel is not used then Word Alignment is not supported for the remaining channels.

All outputs associated with an unused channel should left be unconnected. All inputs (other than Receiver Link Inputs) should be tied to ground. The Receiver Link Inputs (RLINK\_n\_N and RLINK\_n\_P) should be terminated as shown in Figure 1.

Figure 1: Unused RLINK Termination



Lower values of  $R_1$  and  $R_2$  improve noise margin (AC power) at the expense of DC power. Higher values of  $R_1$  and  $R_2$  reduce noise margin but save DC power. The minimum value of  $V_{inp} - V_{inm}$  necessary to give adequate noise margins is 35mV. The best values for  $R_1$  and  $R_2$  are:  $R_1 = R_2 = 2.2k$  ohms. This achieves  $V_{inp} - V_{inm} = 38mV$ .

Other values will work with slightly more power being drawn as long as the following relationships are met:

$$\frac{V_{dd}}{2} \leq V_{cm} \leq \frac{2 \cdot V_{dd}}{3} \qquad \frac{R_2}{2} \leq R_1 \leq R_2 \qquad R_1 + R_2 \leq 4.4k$$

It does not matter which signal is pulled down. The important point is that the other should be pulled up. RLINK\_n\_P may be pulled down and RLINK\_n\_N pulled up. RLINK\_n\_N may be pulled down and RLINK\_n\_P pulled up.

Note : Multiple links may share the same  $R_1$  and  $R_2$  (in parallel) by adjusting  $R_1$  and  $R_2$  according to:

$$R_{1new} = \frac{R_1}{x} \qquad R_{2new} = \frac{R_2}{x}$$

Where “x” is the number of links sharing R1 and R2.

Table 1 lists the connections for the inputs and outputs of each unused channel to minimize power. All unused channels must be connected as shown.

**Table 1: Warplink Pinout and Termination**

Warplink Pinout*	Input/Output	Disposition
XMIT_n_0	I	GND
XMIT_n_1	I	GND
XMIT_n_2	I	GND
XMIT_n_3	I	GND
XMIT_n_4	I	GND
XMIT_n_5	I	GND
XMIT_n_6	I	GND
XMIT_n_7	I	GND
XMIT_n_K	I	GND
XMIT_n_IDLE_B	I	GND
XLINK_n_P	O (link)	N/C
XLINK_n_N	O (link)	N/C
RECV_n_0	O	N/C
RECV_n_1	O	N/C
RECV_n_2	O	N/C
RECV_n_3	O	N/C
RECV_n_4	O	N/C
RECV_n_5	O	N/C
RECV_n_6	O	N/C
RECV_n_7	O	N/C
RECV_n_K	O	N/C
RECV_n_9	O	N/C
RECV_n_IDLE	O	N/C
RECV_n_ERR	O	N/C
RECV_n_RCLK	O	N/C
RLINK_n_P	I (link)	See Figure 1
RLINK_n_N	I (link)	See Figure 1

\* “n” is a placeholder for the channel identifier “A” through “D”.

## 1.2 Power Consumption Estimates

Tables 2 and 3 contain estimated power consumption for various Warlink configurations assuming the guidelines defined in Section 1.1 of this document are followed.

**Table 2: Power Estimates (mW) for 8b10b Mode**

Supply	Condition*	1 active channel	2 active channels	3 active channels	4 active channels
3.3V	Typical	41.0	82.0	123.0	164.0
1.8V	Typical	391.0	519.0	648.0	777.0
Total	Typical	432.0	601.0	771.0	941.0
3.3V	Worst Case	49.0	98.0	147.0	196.0
1.8V	Worst Case	453.0	603.0	753.0	902.0
Total	Worst Case	502.0	701.0	900.0	1098.0

**Table 3: Power Estimates (mW) 10 bit mode**

Supply	Condition*	1 active channel	2 active channels	3 active channels	4 active channels
3.3V	Typical	48.0	96.0	144.0	192.0
1.8V	Typical	391.0	519.0	648.0	777.0
Total	Typical	439.0	615.0	792.0	969.0
3.3V	Worst Case	57.0	114.0	171.0	228.0
1.8V	Worst Case	453.0	603.0	753.0	902.0
Total	Worst Case	510.0	737.0	924.0	1130.0

\* Typical power conditions for 3.3V logic is 3.3V, 40° C, and typical process

Typical power conditions for 1.8V logic is 1.8V, 40° C, and typical process

Worst Case power conditions for 3.3V logic is 3.6V, 105° C, and best case process

Worst Case power conditions for 1.8V logic is 1.95V, 105° C, and best case process



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Freescale Semiconductor Japan Ltd.  
 Headquarters  
 ARCO Tower 15F  
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 Japan  
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[support.japan@freescale.com](mailto:support.japan@freescale.com)

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Freescale Semiconductor Hong Kong Ltd.  
 Technical Information Center  
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